



PTO/SB/08A (10-01)

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Substitute for form 1449/PTO		Complete if known	
		Application Number	10/672,961 (Conf. No.: 9439)
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)		Filing Date	September 26, 2003
		First Named Inventor	Glenn J. Leedy
		Art Unit	2822
		Examiner Name	Monica Lewis
		Attorney Docket Number	ELM-2 Cont. 4
Sheet	1	of	1

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Documents	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
ML		US-4,934,799	06-19-1990	Chu	

Examiner Signature		Date Considered	3/10/04
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All References Have Been Considered: _____
Examiner* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered.
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PTO/SB/08a/b (08-03)

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		Number-Kind Code ² (if known)			
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		US 4,849,857	07-18-1989	Butt et al.	
		US 4,928,058	05-22-1990	Williamson	
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		Country Code ² -Number ⁴ -Kind Code ⁵ (if known)				
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ML		EP 0 224 418 B1	06-03-1987	Fujitsu Limited		
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ML		WO 1990 009093	08-23-1990	Polythetics Inc.		
ML		WO 1992 017901	10-15-1992	Integrated System Assemblies Corporation		

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NON PATENT LITERATURE DOCUMENTS			
Examiner Initials	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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		Svechnikov, S.V.; Kobylatskaya, M.F.; Kimarskii, V.I.; Kaufman, A.P.; Kuzovlev, Yu. I.; Cherepov, Ye. I.; Pomin, B.I.; "A switching plate with aluminum membrane crossings of conductors"; 1972	
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ML		Boyer, P.K.; Moore, C.A.; Solanki, R.; Ritchie, W.K.; Roche, G.A.; Collins, G.J.; "Laser photolytic deposition of thin films"; 1983; pp. 119-27	
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ML		Riley, P.E.; Shelley, A.; "Characterization of a spin-applied dielectric for use in multilevel metallization"; May 1988; pp. 1207-10	
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